

MOSFET - Power, Single N-Channel, Source Down Dual Cool[®] 33, WDFN9 25 V, 0.58 mΩ, 310 A

NTTFSSCH0D7N02X

Features

- Excellent Thermal Conduction by Advanced Source-Down Center Gate Dual-Cooling Package Technology (3.3 x 3.3 mm)
- Ultra Low $R_{DS(on)}$ to Improve System Efficiency
- Low Q_G and Capacitance to Minimize Driving and Switching Losses
- These Devices are Pb-Free, Halogen Free/BFR Free and are RoHS Compliant

Applications

- High Switching Frequency DC-DC Conversion
- Synchronous Rectifier

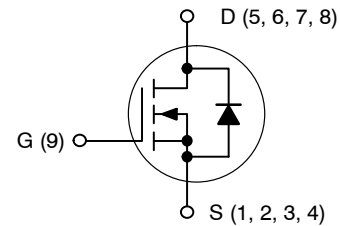
MAXIMUM RATINGS ($T_J = 25^\circ\text{C}$ unless otherwise noted)

Parameter		Symbol	Value	Unit
Drain-to-Source Voltage		V_{DSS}	25	V
Gate-to-Source Voltage		V_{GS}	-12/+16	V
Continuous Drain Current	$T_C = 25\text{ }^{\circ}\text{C}$	I_D	310	A
	$T_C = 100\text{ }^{\circ}\text{C}$		196	
Power Dissipation	$T_C = 25\text{ }^{\circ}\text{C}$	P_D	87	W
Pulsed Drain Current	$T_C = 25\text{ }^{\circ}\text{C}$, $t_p = 100\text{ }\mu\text{s}$	I_{DM}	1342	A
Operating Junction and Storage Temperature Range		T_J, T_{stg}	-55 to +150	$^{\circ}\text{C}$
Source Current (Body Diode)		I_S	146	A
Single Pulse Avalanche Energy ($I_{PK} = 62\text{ A}$)		E_{AS}	192	mJ
Lead Temperature for Soldering Purposes (1/8" from case for 10 s)		T_L	260	$^{\circ}\text{C}$

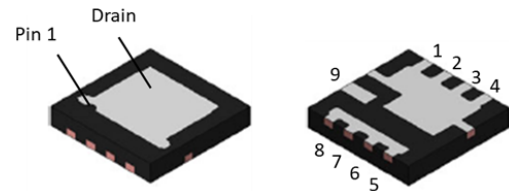
Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

- The entire application environment impacts the thermal resistance values shown, they are not constants and are valid for the particular conditions noted.
- Surface-mounted on FR4 board using a 1 in² pad size, 1 oz Cu pad.
- E_{AS} of 192 mJ is based on started $T_J = 25^\circ\text{C}$, $I_{AS} = 62\text{ A}$, $V_{GS} = 10\text{ V}$, 100% avalanche tested.

$V_{(BR)DS}$	$R_{DS(on)}$ MAX	I_D MAX
25 V	0.58 mΩ @ $V_{GS} = 10\text{ V}$	310 A
	0.80 mΩ @ $V_{GS} = 4.5\text{ V}$	

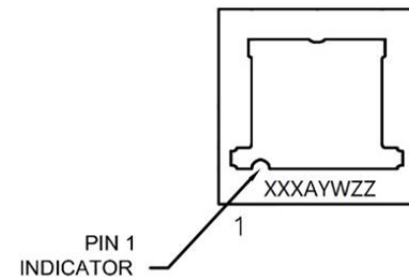


N-CHANNEL MOSFET



WDFN9
CASE 511BX

MARKING DIAGRAM



0D7 = Specific Device Code
A = Assembly Location
YW = Assembly Start Week
ZZ = Assembly Lot Number

ORDERING INFORMATION

See detailed ordering and shipping information on page 6 of this data sheet.

THERMAL CHARACTERISTICS

Parameter	Symbol	Value	Unit
Thermal Resistance, Junction-to-Case (Bottom)	$R_{\theta JCB}$	1.4	°C/W
Thermal Resistance, Junction-to-Case (Top)	$R_{\theta JCT}$	1.2	
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	60	

ELECTRICAL CHARACTERISTICS ($T_J = 25\text{ }^{\circ}\text{C}$ unless otherwise specified)

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
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OFF CHARACTERISTICS

Drain-to-Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS} = 0\text{ V}, I_D = 1\text{ mA}$	25			V
Drain-to-Source Breakdown Voltage Temperature Coefficient	$\Delta V_{(BR)DSS} / \Delta T_J$	$I_D = 1\text{ mA}$, Referenced to $25\text{ }^{\circ}\text{C}$		21		mV/°C
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS} = 20\text{ V}$			10	μA
		$V_{DS} = 20\text{ V}, T_J = 125\text{ }^{\circ}\text{C}$			100	
Gate-to-Source Leakage Current	I_{GSS}	$V_{DS} = 0\text{ V}, V_{GS} = +16\text{ V}$			100	nA

ON CHARACTERISTICS

Drain-to-Source On Resistance	$R_{DS(ON)}$	$V_{GS} = 10\text{ V}, I_D = 24\text{ A}$		0.51	0.58	m Ω
		$V_{GS} = 6\text{ V}, I_D = 19\text{ A}$		0.56	0.65	
		$V_{GS} = 4.5\text{ V}, I_D = 19\text{ A}$		0.66	0.80	
Gate Threshold Voltage	$V_{GS(TH)}$	$V_{GS} = V_{DS}, I_D = 484\text{ }\mu\text{A}$	1.1		2.0	V
Gate Threshold Voltage Temperature Coefficient	$\Delta V_{GS(TH)} / \Delta T_J$	$V_{GS} = V_{DS}, I_D = 484\text{ }\mu\text{A}$		-3		mV/°C
Forward Transconductance	g_{FS}	$V_{DS} = 5\text{ V}, I_D = 24\text{ A}$		190		S

CHARGES, CAPACITANCES & GATE RESISTANCE

Input Capacitance	C_{ISS}	$V_{GS} = 0\text{ V}, V_{DS} = 12\text{ V}, f = 1\text{ MHz}$		3980		pF
Output Capacitance	C_{OSS}			1160		
Reverse Transfer Capacitance	C_{RSS}			124		
Output Charge	Q_{OSS}			22		nC
Total Gate Charge	$Q_{G(TOT)}$	$V_{GS} = 4.5\text{ V}, V_{DD} = 12\text{ V}, I_D = 24\text{ A}$		25		
		$V_{GS} = 6\text{ V}, V_{DD} = 12\text{ V}, I_D = 24\text{ A}$		33		
		$V_{GS} = 10\text{ V}, V_{DD} = 12\text{ V}, I_D = 24\text{ A}$		55		
Threshold Gate Charge	$Q_{G(TH)}$			5.7		
Gate-to-Source Charge	Q_{GS}			9.7		
Gate-to-Drain Charge	Q_{GD}			4.1		
Gate Plateau Voltage	V_{GP}			2.5		V
Gate Resistance	R_G	$f = 1\text{ MHz}$		0.4		Ω

SWITCHING CHARACTERISTICS

Turn-On Delay Time	$t_{d(ON)}$	Resistive Load, $V_{GS} = 0/10\text{ V}, V_{DD} = 12\text{ V},$ $I_D = 24\text{ A}, R_G = 2.5\text{ }\Omega$		4		ns
Rise Time	t_r			6		
Turn-Off Delay Time	$t_{d(OFF)}$			26		
Fall Time	t_f			57		

SOURCE-TO-DRAIN DIODE CHARACTERISTICS

Forward Diode Voltage	V_{SD}	$V_{GS} = 0\text{ V}, I_S = 24\text{ A}$		0.76	1.2	V
		$V_{GS} = 0\text{ V}, I_S = 24\text{ A}, T_J = 125\text{ }^{\circ}\text{C}$		0.63		

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ELECTRICAL CHARACTERISTICS (T_J = 25 °C unless otherwise specified)

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
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SOURCE-TO-DRAIN DIODE CHARACTERISTICS

Reverse Recovery Time	t _{RR}	V _{GS} = 0 V, I _S = 24 A, dI/dt = 700 A/μs, V _{DD} = 12 V		17		ns
Charge Time	t _a			10		
Discharge Time	t _b			7		
Reverse Recovery Charge	Q _{RR}			58		nC

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

TYPICAL CHARACTERISTICS

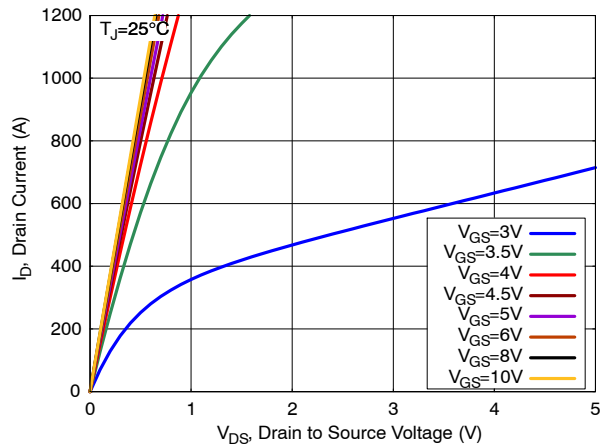


Figure 1. On-Region Characteristics

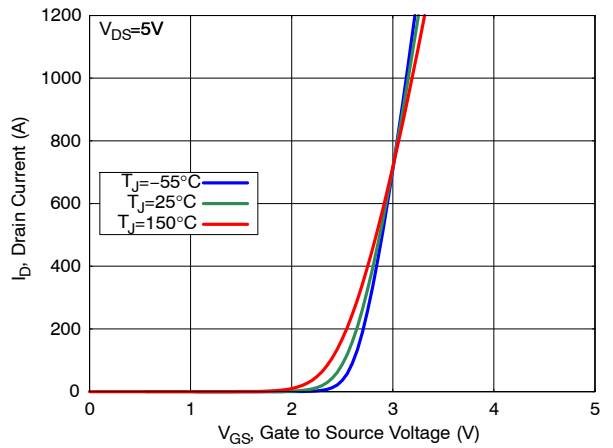


Figure 2. Transfer Characteristics

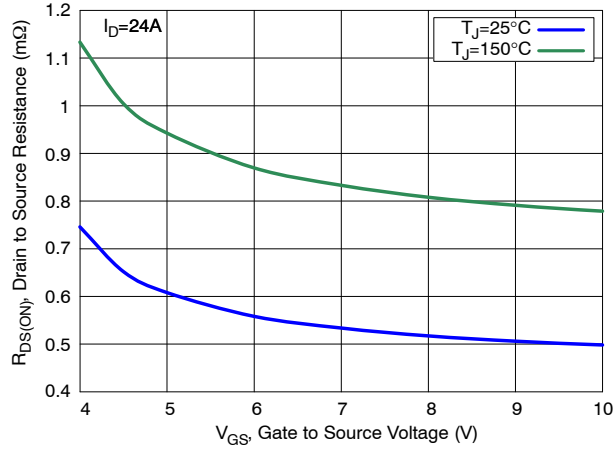


Figure 3. On-Resistance vs. Gate Voltage

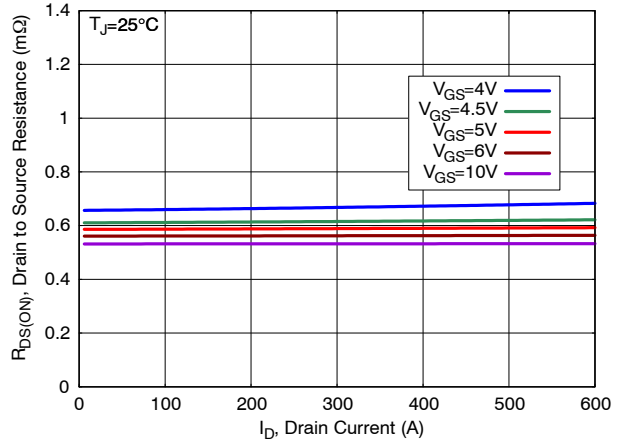


Figure 4. On-Resistance vs. Drain Current

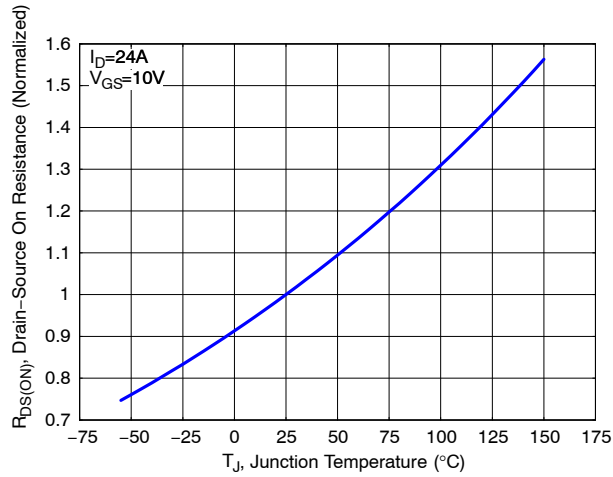


Figure 5. Normalized ON Resistance vs. Junction Temperature

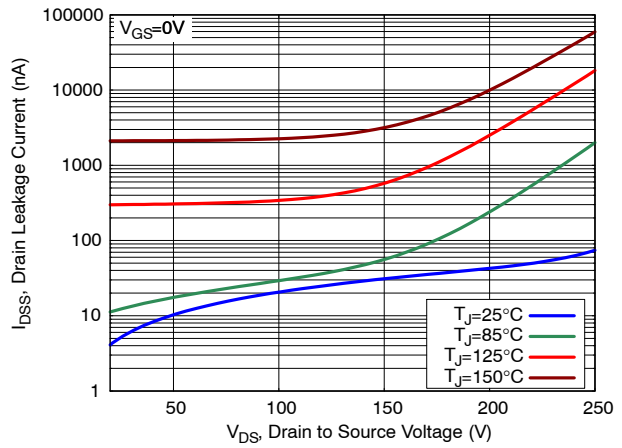


Figure 6. Drain Leakage Current vs. Drain Voltage

TYPICAL CHARACTERISTICS

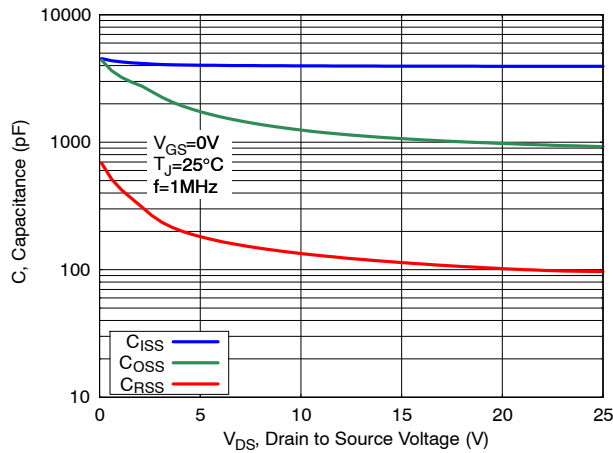


Figure 7. Capacitance Characteristics

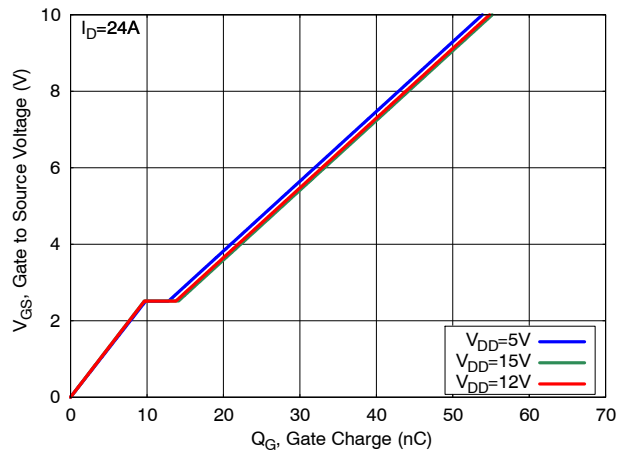


Figure 8. Gate Charge Characteristics

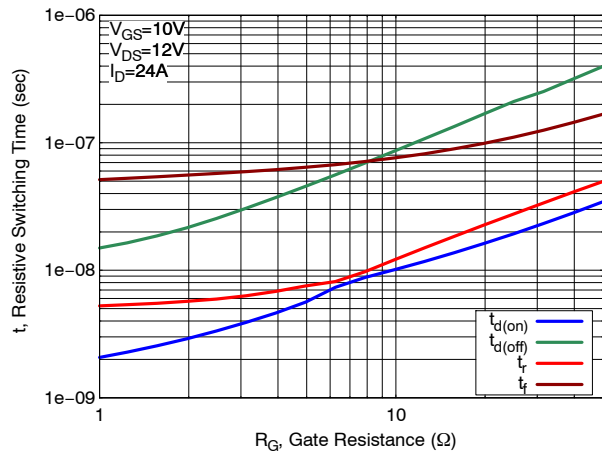


Figure 9. Resistive Switching Time Variation vs. Gate Resistance

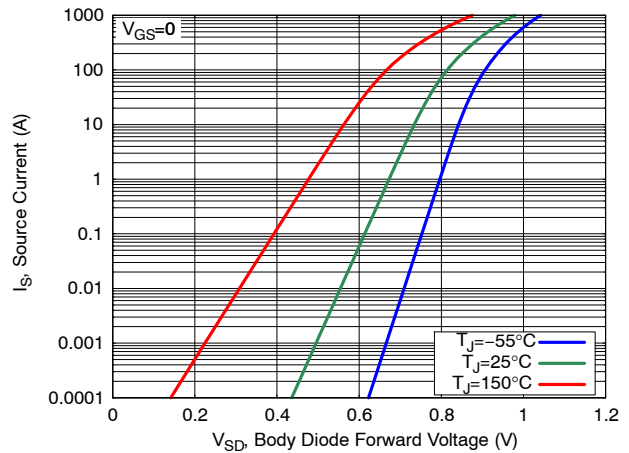


Figure 10. Diode Forward Characteristics

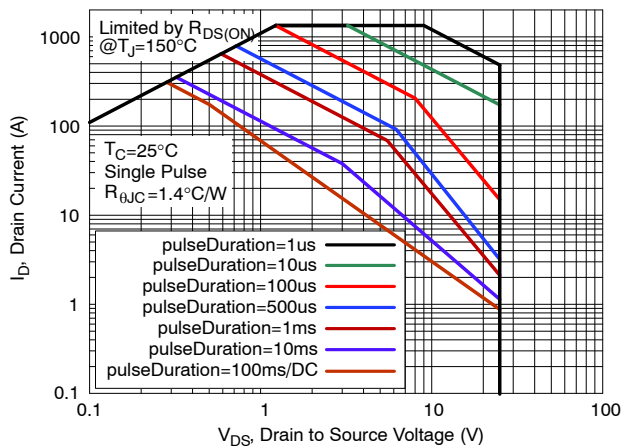


Figure 11. Safe Operating Area (SOA)

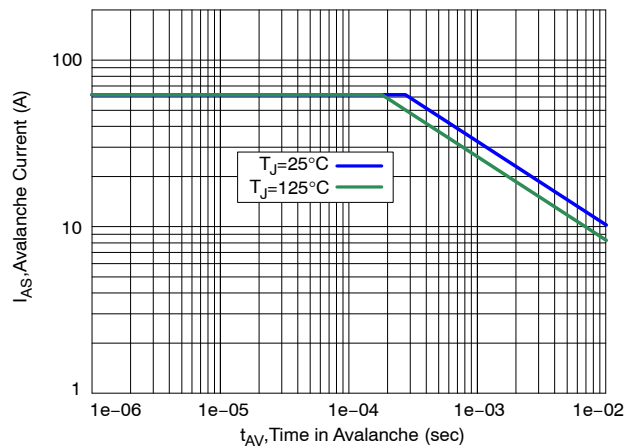


Figure 12. Avalanche Current vs. Pulse Time (UIS)

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TYPICAL CHARACTERISTICS

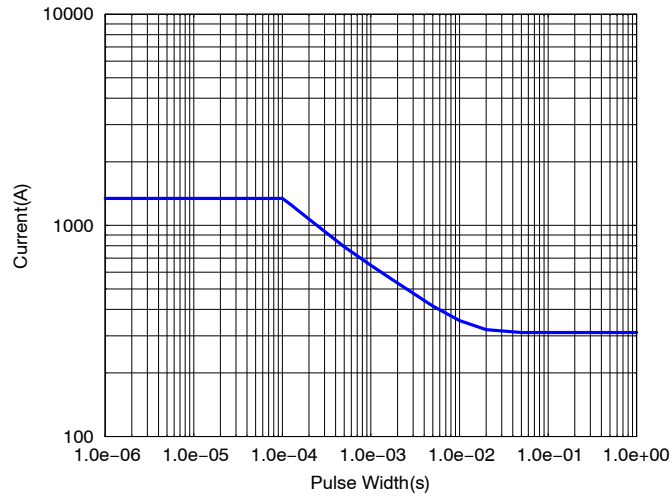


Figure 13. IDM vs. Pulse Width

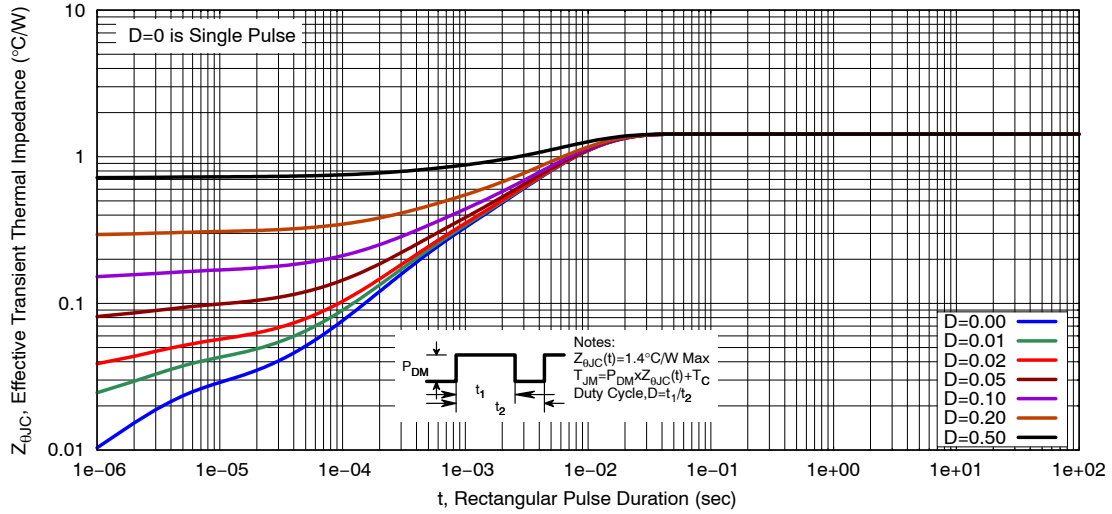


Figure 14. Transient Thermal Response

ORDERING INFORMATION

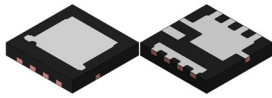
Device	Marking	Package	Shipping†
NTTFSSCH0D7N02X	0D7	WDFN9 (Pb-Free)	5000 / Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, [BRD8011/D](#).

REVISION HISTORY

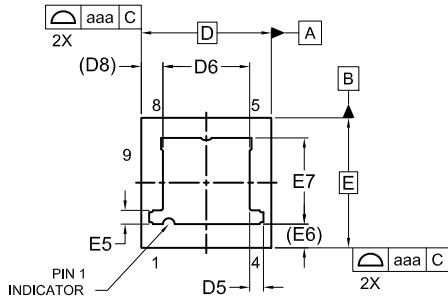
Revision	Description of Changes	Date
3	Replace figure 3	7/7/2025

This document has undergone updates prior to the inclusion of this revision history table. The changes tracked here only reflect updates made on the noted approval dates.

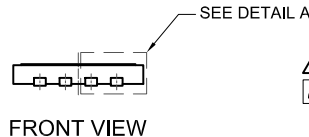


WDFN9 3.30x3.30x0.58, 0.65P
CASE 511BX
ISSUE B

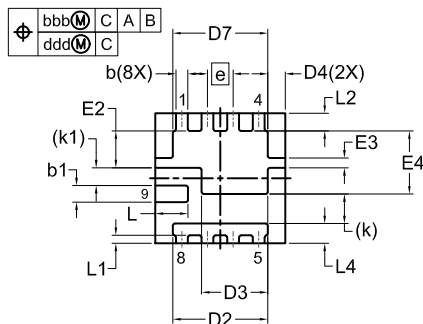
DATE 13 AUG 2024



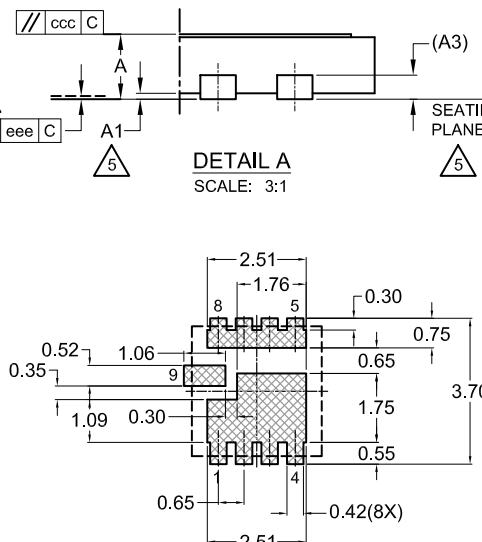
TOP VIEW



FRONT VIEW



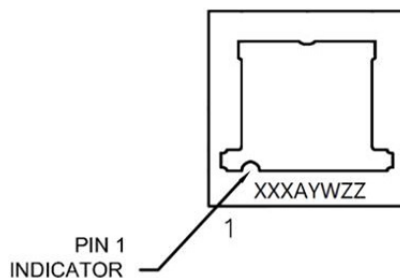
BOTTOM VIEW



LAND PATTERN
RECOMMENDATION

*FOR ADDITIONAL INFORMATION ON OUR PB-FREE STRATEGY AND SOLDERING DETAILS, PLEASE DOWNLOAD THE ONSEMI SOLDERING AND MOUNTING TECHNIQUES REFERENCE MANUAL, SOLDERRM/D.

GENERIC MARKING DIAGRAM*



XXX = Specific Device Code
A = Assembly Location
Y = Year
W = Work Week
ZZ = Assembly Lot Code

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "•", may or may not be present. Some products may not follow the Generic Marking.

NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 2018.
2. CONTROLLING DIMENSION: MILLIMETERS
3. COPLANARITY APPLIES TO THE EXPOSED PADS AS WELL AS THE TERMINALS.
4. DIMENSIONS D1, D2, E1 AND E2 DO NOT INCLUDE MOLD FLASH. SEATING PLANE IS DEFINED BY THE TERMINALS. "A1" IS DEFINED AS THE DISTANCE FROM THE SEATING PLANE TO THE LOWEST POINT ON THE PACKAGE BODY.

UNIT IN MILLIMETERS			
DIM	MIN	NOM	MAX
A	0.53	0.58	0.63
A1	0.00	-	0.05
A3	0.20 REF		
b	0.25	0.30	0.35
b1	0.37	0.42	0.47
D	3.30 BSC		
D2	2.31	2.41	2.51
D3	1.58	1.68	1.78
D4	0.35	0.45	0.55
D5	0.25	0.35	0.45
D6	2.10	2.20	2.30
D7	2.31	2.41	2.51
D8	0.55 REF		
e	0.65 BSC		
E	3.30 BSC		
E2	0.84	0.94	1.04
E3	0.20	0.25	0.30
E4	1.50	1.60	1.70
E5	0.25	0.35	0.40
E6	0.60 REF		
E7	2.10	2.20	2.30
k	0.75 REF		
k1	0.45 REF		
L	0.73	0.83	0.93
L1	0.10	0.20	0.30
L2	0.35	0.45	0.55
L4	0.40	0.50	0.60
aaa	0.10		
bbb	0.10		
ccc	0.10		
ddd	0.05		
eee	0.08		

DOCUMENT NUMBER: 98AON34932H

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DESCRIPTION: WDFN9 3.30x3.30x0.58, 0.65P

PAGE 1 OF 1

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